Supplier Name: Texas Instruments Inc. (DUNS# 00-732-1904)

Contact Info: ti.com/support

Distribute - RoHS and IEC 62474 DB Form/Declaration Type:

06/09/2022 Created on:

Details for "TLV76750DGNR"

Current Product Information

TI part number	Lead finish/Ball material	MSL rating/peak reflow	Assembly site	Package Pins	Package body size (mm)	Total device mass (mg)*
TLV76750DGNR	NIPDAUAG	Level-2-260C-1 YEAR	Ext-Mfg	DGN 8	3x3x1	26.9

*Total Device Mass

The summary mass is a rounded value and will be within approximately +/- 10% of the detailed mass value.

Environmental Ratings Information

RoHS	REACH	Green	IEC 62474 DB	
Yes	Yes	Yes	Yes	

Component Information

				Homogeneous Material Level		Component Level	
Component	Substance	CAS Number	Amount (mg)	Percentage %	ppm	Percentage %	ppm
Bond Wire							
Copper and Its Alloys	Copper	7440-50-8	0.023736	96.676442	966764	0.088375	884
Precious Metals	Gold	7440-57-5	0.000131	0.533561	5336	0.000488	5
Precious Metals	Palladium	7440-05-3	0.000685	2.789997	27900	0.00255	26
Sub-Total			0.024552	100	1000000	0.091413	914
Die Attach Adhesive			-				
Precious Metals	Silver	7440-22-4	0.119957	82.000014	820000	0.44663	4466
Thermoplastics	Ероху	85954-11-6	0.026332	17.999986	180000	0.098041	980
Sub-Total			0.146289	100	1000000	0.544671	5447
Lead Frame			,				
Copper and Its Alloys	Copper	7440-50-8	10.7408	95.9	959000	39.990684	399907
Magnesium and Its Alloys	Magnesium	7439-95-4	0.0196	0.175	1750	0.072976	730
Nickel and Its Alloys	Nickel	7440-02-0	0.3584	3.2	32000	1.334413	13344
Other Inorganic Materials	Silicon	7440-21-3	0.0812	0.725	7250	0.302328	3023
Sub-Total			11.2	100	1000000	41.700401	417004
Lead Frame Plating	•	•					
Nickel and Its Alloys	Nickel	7440-02-0	0.196157	97.299617	972996	0.730342	7303
Precious Metals	Gold	7440-57-5	0.000605	0.300098	3001	0.002253	23
Precious Metals	Palladium	7440-05-3	0.004234	2.100188	21002	0.015764	158
Precious Metals	Silver	7440-22-4	0.000605	0.300098	3001	0.002253	23
Sub-Total			0.201601	100	1000000	0.750611	7506
Mold Compound	•	•					
Other Inorganic Materials	Fused Silica	60676-86-0	13.578283	93.499999	935000	50.555343	505553
Other Plastics and Rubber	Carbon Black	1333-86-4	0.072611	0.499999	5000	0.270349	2703
Thermoplastics	Ероху	85954-11-6	0.871334	6.000002	60000	3.244194	32442
Sub-Total			14.522228	100	1000000	54.069887	540699
Semiconductor Device	•	•			<u> </u>		
Ceramics / Glass	Doped Silicon	7440-21-3	0.763585	100	1000000	2.843018	28430
Sub-Total			0.763585	100	1000000	2.843018	28430
Total			26.858255			100	1000000

Important Note

The ppm calculations are at the homogeneous material level and are maximum concentration values. The ppm displayed represents the homogeneous material with the highest ppm

for that substance. The amount (mg) calculations represent the maximum total amount of each substance within the component.

The ppm calculations are at the component level and are average concentration values. The amount (mg) calculations represent the average total amount of each substance within the component. See Glossary of Terms for more details.

Important Part Information

There is a remote possibility the Customer Part Number (CPN) your company uses could reference more than one TI part number. This is due to two or more users (EMSIs or subcontractors) using the same CPN for different TI part numbers. If this occurs, please check your Customer Part Number and cross reference it with the TI part number seen on this page.

Product Content Methodology

For an explanation of the methods used to determine material weights, See Product Content Methodology

Material Declaration Certificate for Semiconductor IC Packaged Products

TI certifies that the material content information provided by TI is representative and accurate to the best of their knowledge based on material information provided by its suppliers and their combination into finished IC packaged products. TI semiconductor products designated to be "Pb-free", "Green" or "RoHS Exempt" fully meets the latest EU RoHS Directive requirements along with other legislation as seen in the former JIG-101 list that has been transferred to the IEC 62474 database.

Important Information/Disclaimer

TI bases its material content information on information provided by third-party suppliers and has taken, and continues to take, reasonably diligent steps to provide any required or available information. TI may not have conducted destructive testing or chemical analysis on incoming materials and chemicals. TI and TI suppliers may consider certain information to be proprietary, and thus certain information may not be available for release by TI. The material content information is provided by TI "as is."

For additional information, please contact TI customer support.

Signature: (click here for a fuller statement with a signed certificate)

Name/Title: Hubie Payne, Vice President, Worldwide SC Quality For further environmental statements, please go to www.ti.com/ecoinfo Created on: 06/09/2022

RoHS: Means TI semiconductor products that are compliant with the current RoHS requirement that the maximum concentration values of the ten substances listed in RoHS Annex II do not exceed 0.1 % by weight in homogeneous materials. Where designed to be soldered at high temperatures, TI semiconductor products labeled as "RoHS Compliant" are suitable for use in specified lead-free processes. TI may also reference these types of semiconductor products as "Pb-Free." These TI semiconductor products are also fully compliant with GADSL and the IEC 62474 database for electronic requirements.

RoHS Exempt: Means TI semiconductor products that contain lead (Pb) above the RoHS Annex II threshold, but that fall within one of the specific RoHS exemptions noted above or documented in http://www.ti.com/lit/pdf/szzq088

Green: Means the content of Chlorine (CI) and Bromine (Br)-based flame retardants meet JS709B low halogen requirements of <=1 000ppm threshold; Antimony trioxide (Sb203) contained in halogen based flame retardant materials meets the <=1 000ppm threshold requirement; and Beryllium Oxide (BeO) is <=1000ppm.